

AMENDMENTS TO THE CLAIMS:

Cancel claims 48-50 and 55.

Amend claims 56-58 as follows:

56. (Amended) A semiconductor element module, comprising:
a package;

a semiconductor element within said package;

a plurality of leads for connecting said semiconductor element to an external circuit,
said plurality of leads each having a wide portion connected to a side surface of said package
and a narrow portion that extends downwardly beyond the bottom surface of said package,
wherein said wide portion extends below the bottom edge of said side surface, and
a level difference in said side surface of said package adjacent said bottom surface
that forms a space between the wide portion of each lead that extends below the bottom edge
of said side surface and the bottom of said package.

57. (Amended) The semiconductor element module of claim 56, further including
a brazing material disposed within said level difference for securing the connection of said
leads to said package.

58. (Amended) The semiconductor element module of claim 56, wherein said
narrow portions of said leads are bent outwardly away from said package to form a mounting
surface.